



72nd
International
Electron
Devices
Meeting

Devices at the Heart of the Intelligence Revolution

2026 International
Electron Devices
Meeting

December 12-16, 2026

Hilton San Francisco Union Square
San Francisco, CA

IEDM is pleased to announce increased
technical focus in the area of:

MODELING and SIMULATION (MS)

Topics

Papers are solicited in the following themes of interest:

- Technology CAD and AI-driven benchmarking
- Advanced logic and memory device modeling
- Atomistic material, process, and interconnect simulation
- Compact models for DTCO and STCO
- Alternative computing device modeling including Neuromorphic and In-Memory Computing
- Optoelectronics, display and image systems modeling
- Sensors, MEMS and bioelectronics modeling
- Power, millimeter-wave, and analog technology modeling

New or trending areas include:

- Multi-scale simulation with Generative AI and hybrid techniques
- Advanced packaging, Chiplet-based, and 3D integration modeling
- Thermal modeling for high-power density and 3D stacks
- Low-temperature and quantum-resilient, and quantum device modeling
- Device modeling for photonics and optical interconnects
- Device modeling for in-memory and in-sensor computing

Paper Submission

Deadline: July 16th

Single submission of final, four-page paper



For More Information

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Social Networks: ieee-iedm.org/social-media

